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GUEST EDITORIAL

Introduction to the Special Issue on the 2021 Symposium on VLSI Circuits *Y. Oike and B. Nikolić* 983

SPECIAL ISSUE PAPERS

Versa: A 36-Core Systolic Multiprocessor With Dynamically Reconfigurable Interconnect and Memory	<i>S. Kim, M. Fayazi, A. Daftardar, K.-Y. Chen, J. Tan, S. Pal, T. Ajayi, Y. Xiong, T. Mudge, C. Chakrabarti, D. Blaauw, R. Dreslinski, and H.-S. Kim</i>	986
OmniDRL: An Energy-Efficient Deep Reinforcement Learning Processor With Dual-Mode Weight Compression and Sparse Weight Transposer	<i>J. Lee, S. Kim, S. Kim, W. Jo, J.-H. Kim, D. Han, and H.-J. Yoo</i>	999
CHIMERA: A 0.92-TOPS, 2.2-TOPS/W Edge AI Accelerator With 2-MByte On-Chip Foundry Resistive RAM for Efficient Training and Inference	<i>K. Prabhu, A. Gural, Z. F. Khan, R. M. Radway, M. Giordano, K. Koul, R. Doshi, J. W. Kustin, T. Liu, G. B. Lopes, V. Turbiner, W.-S. Khwa, Y.-D. Chih, M.-F. Chang, G. Lallement, B. Murmann, S. Mitra, and P. Raina</i>	1013
HERMES-Core—A 1.59-TOPS/mm ² PCM on 14-nm CMOS In-Memory Compute Core Using 300-ps/LSB Linearized CCO-Based ADCs	<i>R. Khaddam-Aljameh, M. Stanisavljevic, J. F. Mas, G. Karunaratne, M. Brändli, F. Liu, A. Singh, S. M. Müller, U. Egger, A. Petropoulos, T. Antonakopoulos, K. Brew, S. Choi, I. Ok, F. L. Lie, N. Saulnier, V. Chan, I. Ahsan, V. Narayanan, S. R. Nandakumar, M. Le Gallo, P. A. Francese, A. Sebastian, and E. Eleftheriou</i>	1027
SRAM Write- and Performance-Assist Cells for Reducing Interconnect Resistance Effects Increased With Technology Scaling	<i>K. Cho, H. Choi, I. J. Jung, J. Oh, T. W. Oh, K. Kim, G. Kim, T. Choi, C. Sim, T. Song, and S.-O. Jung</i>	1039
A Patient-Specific Closed-Loop Epilepsy Management SoC With One-Shot Learning and Online Tuning	<i>M. Zhang, L. Zhang, C.-W. Tsai, and J. Yoo</i>	1049
A Light-Tolerant Wireless Neural Recording IC for Motor Prediction With Near-Infrared-Based Power and Data Telemetry	<i>J. Lim, J. Lee, E. Moon, M. Barrow, G. Atzeni, J. G. Letner, J. T. Costello, S. R. Nason, P. R. Patel, Y. Sun, P. G. Patil, H.-S. Kim, C. A. Chestek, J. Phillips, D. Blaauw, D. Sylvester, and T. Jang</i>	1061

Efficient RF-PA Two-Chip Supply Modulator Architecture for 4G LTE and 5G NR Dual-Connectivity RF Front End		
..... <i>J.-S. Paek, D. Kim, J.-Y. Han, Y. Choo, J.-S. Bang, S. Park, J. Baek, T. Nomiya, I.-H. Kim, and J. Lee</i>		1075
A 32-A, 5-V-Input, 94.2% Peak Efficiency High-Frequency Power Converter Module Featuring Package-Integrated Low-Voltage GaN nMOS Power Transistors	<i>N. Desai, H. W. Then, J. Yu, H. K. Krishnamurthy, W. J. Lambert, N. Butzen, S. Weng, C. Schaef, K. Radhakrishnan, K. Ravichandran, J. W. Tschanz, and V. De</i>	1090
OTA-Free 1-1 MASH ADC Using Fully Passive Noise-Shaping SAR & VCO ADC	<i>S. Tannirkulam Chandrasekaran, S. P. Bhanushali, S. Pietri, and A. Sanyal</i>	1100
A 10.1-ENOB, 6.2-fJ/conv.-step, 500-MS/s, Ringamp-Based Pipelined-SAR ADC With Background Calibration and Dynamic Reference Regulation in 16-nm CMOS	<i>J. Lagos, N. Markulić, B. Hershberg, D. Dermit, M. Shrivastava, E. Martens, and J. Craninckx</i>	1112
2.45 e-RMS Low-Random-Noise, 598.5 mW Low-Power, and 1.2 kfps High-Speed 2-Mp Global Shutter CMOS Image Sensor With Pixel-Level ADC and Memory	<i>M.-W. Seo, M. Chu, H.-Y. Jung, S. Kim, J. Song, D. Bae, S. Lee, J. Lee, S.-Y. Kim, J. Lee, M. Kim, G.-D. Lee, H. Shim, C. Um, C. Kim, I.-G. Baek, D. Kwon, H. Kim, H. Choi, J. Go, J. Ahn, J.-K. Lee, C.-R. Moon, K. Lee, and H.-S. Kim</i>	1125
A Delta Sigma-Modulated Sample and Average Common-Mode Feedback Technique for Capacitively Coupled Amplifiers in a 192-nW Acoustic Analog Front-End	<i>R. Rothe, M. Cho, K. Choo, S. Jeong, S. Oh, J. Lee, D. Sylvester, and D. Blaauw</i>	1138
A -121.5-dB THD Class-D Audio Amplifier With 49-dB LC Filter Nonlinearity Suppression	<i>H. Zhang, M. Berkhout, K. A. A. Makinwa, and Q. Fan</i>	1153
A Self-Adapted Two-Point Modulation Type-II Digital PLL for Fast Chirp Rate and Wide Chirp-Bandwidth FMCW Signal Generation	<i>W. Deng, Z. Chen, H. Jia, A. Yan, S. Sun, G. Chen, Z. Wang, and B. Chi</i>	1162
A 43 nW, 32 kHz, ± 4.2 ppm Piecewise Linear Temperature-Compensated Crystal Oscillator With $\Delta\Sigma$ -Modulated Load Capacitance	<i>S. Park, J.-H. Seol, L. Xu, S. Cho, D. Sylvester, and D. Blaauw</i>	1175
Silicon Photonic Microring-Based 4×112 Gb/s WDM Transmitter With Photocurrent-Based Thermal Control in 28-nm CMOS	<i>J. Sharma, Z. Xuan, H. Li, T. Kim, R. Kumar, M. N. Sakib, C.-M. Hsu, C. Ma, H. Rong, G. Balamurugan, and J. Jaussi</i>	1187
A 1.24-pJ/b 112-Gb/s (870 Gb/s/Mm) Transceiver for In-Package Links in 7-nm FinFET	<i>C. F. Poon, W. Zhang, J. Cho, S. Ma, Y. Wang, Y. Cao, A. Laraba, E. Ho, W. Lin, D. Z. Wu, K. H. Tan, P. Upadhyaya, and Y. Frans</i>	1199
A 28-GHz Phased-Array Relay Transceiver for 5G Network Using Vector-Summing Backscatter With 24-GHz Wireless Power and LO Transfer	<i>M. Ide, A. Shirane, K. Yanagisawa, D. You, J. Pang, and K. Okada</i>	1211
A mm-Wave Switched-Capacitor RFDAC	<i>H. M. Nguyen, J. S. Walling, A. Zhu, and R. B. Staszewski</i>	1224